

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
 - Class Q Military
 - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)
- Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

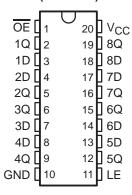
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (N) and Ceramic (J) DIPs

description

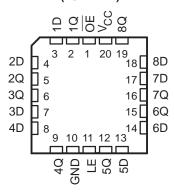
The eight latches of the 'ABT373 are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

SN54ABT373 . . . J OR W PACKAGE SN74ABT373 . . . DB, DW, N, OR PW PACKAGE (TOP VIEW)



SN54ABT373 . . . FK PACKAGE (TOP VIEW)



OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT373 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT373 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE (each latch)

	INPUTS		OUTPUT
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q ₀
Н	Χ	Χ	Z



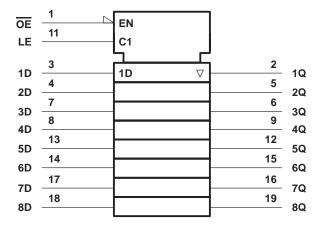
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

TEXAS INSTRUMENTS

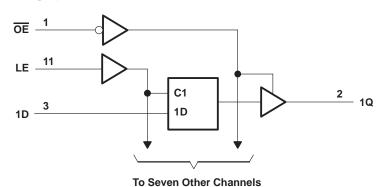
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logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power	er-off state, V _O –0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT3	373 96 mA
SN74ABT3	373 128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	−50 mA
Package thermal impedance, θ _{JA} (see Note 2): DB pa	ckage 115°C/W
DW pa	ackage 97°C/W
N pack	kage 67°C/W
PW pa	ackage 128°C/W
Storage temperature range, T _{stg}	

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 3)

			SN54A	BT373	SN74A	BT373	UNIT
			MIN	MAX	MIN	MAX	UNII
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2		2		V
VIL	Low-level input voltage			0.8		0.8	V
٧ _I	Input voltage		0	VCC	0	VCC	V
IOH	High-level output current			-24		-32	mA
IOL	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED		TEGT COMPLETION	10	Т	A = 25°C	;	SN54A	BT373	SN74A	BT373	LINUT
PARAMETER		TEST CONDITION	NS	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNIT
VIK	$V_{CC} = 4.5 V$,	$I_{I} = -18 \text{ mA}$				-1.2		-1.2		-1.2	V
	$V_{CC} = 4.5 V$,	$I_{OH} = -3 \text{ mA}$		2.5			2.5		2.5		
\/	V _{CC} = 5 V,	$I_{OH} = -3 \text{ mA}$		3			3		3		V
VOH	V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$		2			2				V
	vCC = 4.5 v	$I_{OH} = -32 \text{ mA}$		2*					2		
Voi	V _{CC} = 4.5 V	I _{OL} = 48 mA				0.55		0.55			V
VOL	VCC = 4.5 V	I _{OL} = 64 mA				0.55*				0.55	V
V _{hys}					100						mV
lį	$V_{CC} = 5.5 \text{ V},$	$V_I = V_{CC}$ or GND	1			±1		±1		±1	μΑ
lozh	$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.7 \text{ V}$				10‡		10‡		10‡	μΑ
lozL	$V_{CC} = 5.5 \text{ V},$	$V_0 = 0.5 V$				-10 [‡]		-10 [‡]		-10 [‡]	μΑ
l _{off}	$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$				±100				±100	μΑ
ICEX	$V_{CC} = 5.5 \text{ V},$	$V_0 = 5.5 V$	Outputs high			50		50		50	μΑ
ΙΟ§	$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.5 \text{ V}$		- 50	-100	-180	-50	-180	-50	-180	mA
	.,		Outputs high		1	250		250		250	μΑ
Icc	$V_{CC} = 5.5 \text{ V}, \text{ I}_{C}$ $V_{I} = V_{CC} \text{ or G}$		Outputs low		24	30		30		30	mA
	11-100 01		Outputs disabled		0.5	250		250		250	μΑ
ΔICC¶	V _{CC} = 5.5 V, C Other inputs at	One input at 3.4 V, V _{CC} or GND				1.5		1.5		1.5	mA
C _i	$V_{I} = 2.5 \text{ V or } 0.$.5 V			3						pF
Co	$V_0 = 2.5 \text{ V or } 0$	0.5 V			6						pF

 $[\]begin{tabular}{l}^*$ On products compliant to MIL-PRF-38535, this parameter does not apply.



[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡]This data sheet limit may vary among suppliers.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[¶] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

SN54ABT373, SN74ABT373 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

SCBS155D - JANUARY 1991 - REVISED MAY 1997

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

					SN54A	BT373		
				V _{CC} =	= 5 V, 25°C	MIN	MAX	UNIT
				MIN	MAX			
t _W	Pulse duration, LE high			3.3		3.3		ns
t	Satura time, data bafara I E	High		2.2		2.5		ns
tsu	Setup time, data before LE↓	Low		2.2		2.5		115
t _h	Hold time, data after LE↓	High o	r low	2.2		2.5		ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				SN74A	BT373		
			V _C (; = 5 V, = 25°C	MIN	MAX	UNIT
			MIN	I MAX	1		
t _W	Pulse duration, LE high		3.3	3	3.3		ns
	Cotion time and the before I.E.	High	1.9)	1.9		ns
t _{su}	Setup time, data before LE↓	Low	1.5	;	1.5		115
t _h	Hold time, data after LE↓	High or I	ow 1		1		ns

SN54ABT373, SN74ABT373 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

SCBS155D - JANUARY 1991 - REVISED MAY 1997

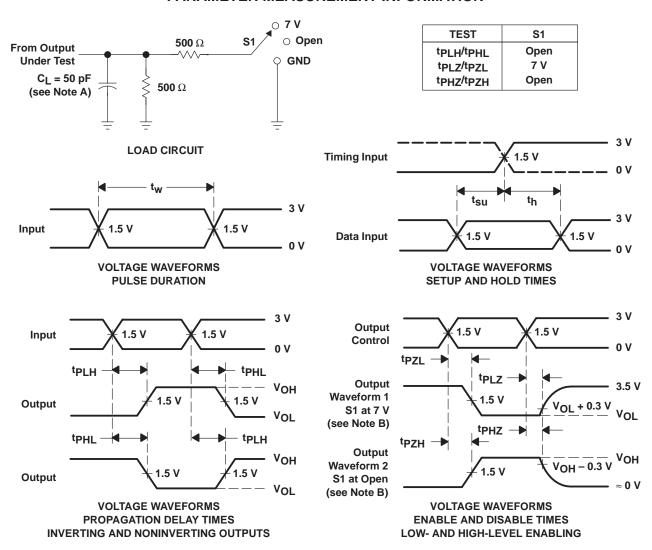
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

				SN	54ABT3	73		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _C	C = 5 V \ = 25°C	/, ;	MIN	MAX	UNIT
			MIN	TYP	MAX			
^t PLH	D	Q	1.9	3.9	5.4	1.3	6.8	ns
t _{PHL}	В	ά	2.2	4.2	5.7	2	7	115
t _{PLH}	LE	Q	2.2	4.6	6.1	1.8	7.7	ns
t _{PHL}	LL	ά	3.2	5.2	6.7	2.5	7.7	115
^t PZH	ŌĒ	Q	1.2	3.2	5.5	1	6.2	ns
t _{PZL}	OE .	ά	2	4.7	6.2	1.5	7.2	115
^t PHZ	ŌĒ	Q	2.5	4.9	6.4	2.4	8	ns
t _{PLZ}	OE OE		2	4.5	6	2	7	115

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	۷ ₀ ۲٫	C = 5 V \ = 25°C	/, ;	MIN	MAX	UNIT
			MIN	TYP	MAX			
t _{PLH}	D	Q	1.9	3.9	5.4	1.9	5.9	20
t _{PHL}	D	Q	2.2	4.2	5.7	2.2	6.2	ns
^t PLH	LE	Q	2.2	4.6	6.1	2.2	6.6	ns
t _{PHL}	LL	Q	3.2	5.2	6.7	3.2	7.2	115
^t PZH	ŌĒ	Q	1.2	3.2	4.7	1.2	5.2	no
t _{PZL}	OE .	Q	2.7	4.7	6.2	2.7	6.7	ns
t _{PHZ}	ŌĒ	Q	2.5	4.9	6.4	2.5	6.9	
t _{PLZ}	OE OE	Q I	2	4.5	6	2	6.5	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{Q} = 50 Ω , t_{f} \leq 2.5 ns, t_{f} \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







11-Jul-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	-	Pins	-	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)		(3)		(4/5)	
5962-9321801Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	-55 to 125	5962- 9321801Q2A SNJ54ABT 373FK	Samples
5962-9321801QRA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Call TI	-55 to 125	5962-9321801QR A SNJ54ABT373J	Samples
5962-9321801QSA	ACTIVE	CFP	W	20	1	TBD	Call TI	Call TI	-55 to 125	5962-9321801QS A SNJ54ABT373W	Samples
SN74ABT373-W	ACTIVE	WAFERSALE	YS	0	7114	TBD	Call TI	Call TI			Samples
SN74ABT373DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI	-40 to 85		
SN74ABT373DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB373	Samples
SN74ABT373DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB373	Samples
SN74ABT373DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB373	Samples
SN74ABT373DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT373	Samples
SN74ABT373DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT373	Samples
SN74ABT373DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT373	Samples
SN74ABT373DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT373	Samples
SN74ABT373DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT373	Samples
SN74ABT373DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT373	Samples
SN74ABT373N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74ABT373N	Samples
SN74ABT373NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74ABT373N	Samples





11-Jul-2013

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)		(3)		(4/5)	
SN74ABT373NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT373	Samples
SN74ABT373NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT373	Samples
SN74ABT373NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT373	Samples
SN74ABT373PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB373	Samples
SN74ABT373PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB373	Samples
SN74ABT373PWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB373	Samples
SN74ABT373PWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI	-40 to 85		
SN74ABT373PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB373	Samples
SN74ABT373PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB373	Samples
SN74ABT373PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB373	Samples
SNJ54ABT373FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9321801Q2A SNJ54ABT 373FK	Samples
SNJ54ABT373J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9321801QR A SNJ54ABT373J	Samples
SNJ54ABT373W	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9321801QS A SNJ54ABT373W	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.



PACKAGE OPTION ADDENDUM

11-Jul-2013

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54ABT373, SN74ABT373:

Catalog: SN74ABT373

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Military: SN54ABT373

NOTE: Qualified Version Definitions:

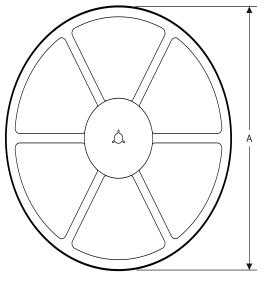
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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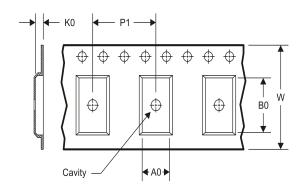
TAPE AND REEL INFORMATION

REEL DIMENSIONS





TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

All ulfrierisions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT373DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ABT373DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ABT373NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74ABT373PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

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*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT373DBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74ABT373DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ABT373NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74ABT373PWR	TSSOP	PW	20	2000	367.0	367.0	38.0

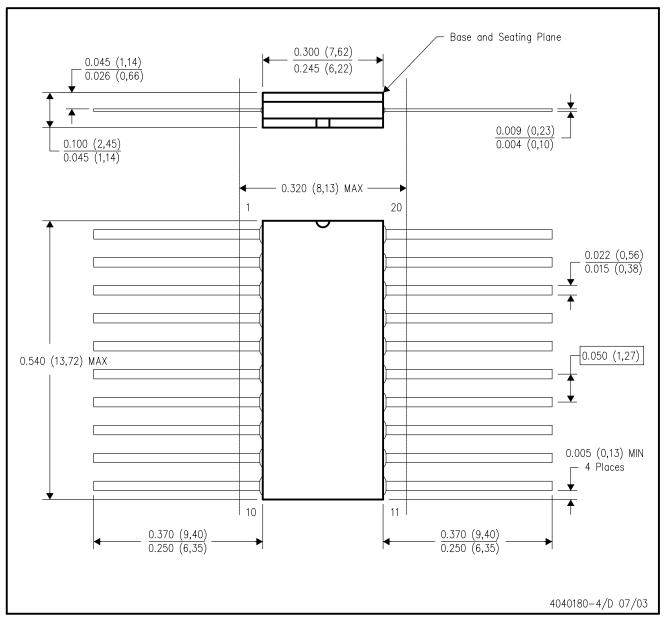
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

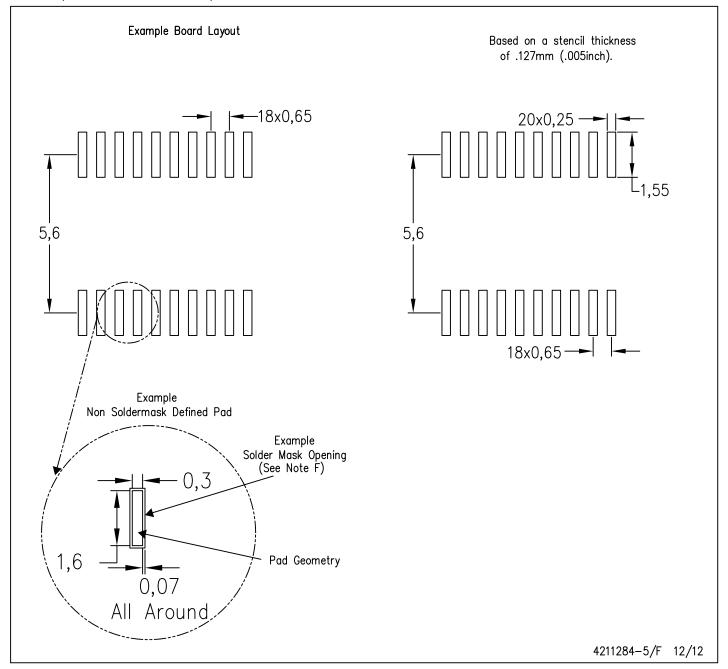


- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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